PRODUCT CHANGE NOTICE

Product Improvement – Wafer Backside Material and Die Attach Process Change for Intersil EL1848*, EL7513* and EL7518* Products

Refer to:
PCN04042

Date: August 20, 2004

August 20, 2004

To: Our Valued Intersil Customers

Subject: **Product Improvement – Wafer Backside Material and Die Attach Process Change for Intersil EL1848*, EL7513* and EL7518* Products**

Intersil's commitment to the concepts of total quality management, customer satisfaction, and continuous improvement is supported by a strategy of manufacturing changes to enhance quality and reliability. This notice is to inform you of a change in the wafer backside material and die attach process for the EL1848*, EL7513*, and EL7518* series products. The qualification activity is in process.

These changes are intended to provide a more robust device and will not affect the form, fit, function, or interchangeability of product. The wafer backside material is changing from gold to bare silicon. The die attach method is changing to a multi layer process designed to increase its thickness during device assembly, with no change to the die attach material. There will be no change in the package external dimensions or moisture sensitivity level.

The qualification plan is designed using JEDEC and other applicable industry standards and is contained in Attachment A. Details of the qualification activity will be available upon completion by request. The remainder of the manufacturing operations (assembly, product electrical testing, shipment, etc.) will continue to be processed to established conditions and systems.

There will be no change in external marking of the packaged parts. Parts affected by this change are identifiable via Intersil's internal traceability system.

Intersil will take all necessary actions to conform to customer requirements ensuring the continued high quality and reliability of products being supplied. Customers may expect to receive product affected by this change beginning immediately.

If you have concerns with this change notice, Intersil must hear from you immediately. Please contact the nearest Intersil Sales Office or call the Intersil Corporate hot line at 1-888-468-3774, in the United Sates, or 1-321-724-7143 outside of the United States.

Jon Brewster

Jon Brewster
Intersil Corporation PCN04042

Cc: A. Baluni M. Lanahan B. Hawthorne

Products Affected – PCN04042

- EL1848IWT
- EL1848IWT-T7
- EL1848IWT-T7A
- EL1848IWTZ
- EL1848IWTZ-T7
- EL1848IWTZ-T7A
- EL7513AIWT
- EL7513AIWT-T7
- EL7513AIWT-T7A
- EL7513AIWTZ
- EL7513AIWTZ-T7
- EL7513AIWTZ-T7A
- EL7513IWT
- EL7513IWT-EVAL
- EL7513IWT-T13
- EL7513IWT-T7
- EL7513IWT-T7A
- EL7513IWTZ
- EL7513IWTZ-T7
- EL7513IWTZ-T7A
- EL7518IWT
- EL7518IWT-T7
- EL7518IWT-T7A
- EL7518IWTZ
- EL7518IWTZ-T7
- EL7518IWTZ-T7A

Appendix A – Package Qualification Plan – PCN04042

Test	Conditions	Sample
Temp Cycle	MIL-STD-883, Method 1010 -65°C/+150°C, 1000 cycles	76
Temp/Humidity Bias HAST	JEDEC JESD22-A110-B 130°C/85%RH with BIAS 96 hrs	45
Pressure Pot **or** **Unbiased HAST**	JEDEC Std-22-A102, 168 hrs. unbiased, 121°C, 100%RH at 2 atm JEDEC JESD22-A110-B 130°C/85%RH without BIAS 168 hrs	45
Moisture Sensitivity	IPC/JEDEC J-STD-020B with IR Reflow at 260°C Std package	22
High Temp Storage	MIL-STD-883, Method 1008, 1000 hrs. unbiased bake at 150°C	22